GLOSSARY

This glossary contains certain technical terms used in this document in connection with our Company and our business. Such terms and their meanings may not correspond to standard industry definitions or usage.

"ADAS"	advanced driver assistance system, which is designed to assist drivers in the operation and safety of vehicles, by utilizing various sensors, cameras and software algorithms to provide additional functionalities and enhance the driving experience
"AEC-Q"	Automotive Electronic Council qualification standard, which is derived by AEC component technical committee to electrical components and their qualification requirement
"AEC-Q100"	AEC-Q100 standard, a set of rigorous requirements and tests that electronic components must pass to ensure their suitability for use in automotive applications. The AEC-Q100 standard is widely recognized and adopted in the automotive industry and is an important consideration in the design and manufacturing of electronic components for automotive applications
"AI"	artificial intelligence, which refers to the ability of a machine or computer system to perform tasks that typically require human intelligence
"AIoT"	artificial intelligence of things, a combination of AI and IoT
"AI Scaler"	our ASIC-based scaler
"AMOLED"	active matrix organic light emitting diode, a high-quality display technology known for being brighter, thinner and more power-efficient
"ARM®"	advanced RISC machine, a processor architecture based on the reduced instruction set, with low power consumption and high energy efficiency as its core goals. ARM® represents a registered trademark
"ASIC"	application-specific IC customized to the needs of a specific application
"ASIL"	automotive safety integrity level, a risk classification system defined by ISO 26262 and there are four ASIL levels identified by the standard, namely ASIL-A, ASIL-B, ASIL-C and ASIL-D, among which ASIL-D dictates the highest integrity requirements on the product and ASIL-A the lowest
"automotive-grade"	an automotive-grade chip refers to a chip that is specifically designed, manufactured and qualified to meet the stringent requirements and standards of the automotive industry (such as AEC-Q100)
"BOM"	bill of materials
"CAGR"	compound annual growth rate
"CPU"	central processing unit, an integrated circuit that serves as the computational and control core of an electronic product

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"DSC decoding"	display stream compression, a lossless display compression standard developed for reducing the bandwidth required to transmit high-resolution display data across interfaces
"EAL4+"	Evaluation Assurance Level, which ranks security evaluations on a scale from one to seven, with EAL4+ representing one of the highest levels achievable for commercial security solutions
"edge AI"	a technology paradigm that combines the capabilities of AI with edge computing, deploying AI algorithms and models directly on edge devices, such as AIoT sensors, smartphones, industrial machines and other local computing devices
"EMC"	electromagnetic compatibility, the ability of electronic devices and systems to function properly in their electromagnetic environment without causing or experiencing interference
"EV"	electric vehicle, a vehicle that is powered entirely or primarily by electricity, typically using a battery and electric motor instead of an internal combustion engine
"fabless"	the development, design and sale of semiconductor chips while outsourcing their manufacturing to external parties
"FLASH"	flash memory, a type of non-volatile semiconductor memory IC, which retains stored information even when powered off, featuring the ability to be repeatedly read, erased and written, and is considered a major category of memory product
"FPGA"	field-programmable gate array, a type of reconfigurable semiconductor device that can be programmed to perform different logic functions after manufacturing
"HoD"	hands-off detection
"Hz"	unit of frequency
"integrated circuit" or "IC"	integrated circuits, a set of electronic circuits on one small plate of semiconductor material
"ISO"	International Organization for Standardization, an international non-governmental organization that develops and publishes standards to ensure quality, safety and efficiency across various industries
"ISO 26262"	an international standard for automotive functional safety which applies to electrical and electronic systems consisting of hardware and software components
"L2"	level 2 of intelligent driving which can assist drivers in controlling speed and steering, such as help with stop-and-go traffic by maintaining the distance between the driver's vehicle and the vehicle in front, and providing steering assist by centering the vehicle within the lane, while still requiring drivers to have hands on the wheel and be ready to take control at any given moment

"L3"	level 3 of intelligent driving, or conditional automation, which allows vehicles to drive themselves, but only under ideal conditions and with limitations, such as limited-access divided highways at a certain speed and parking lots, where drivers are still required behind the wheel whereas their hands are off the wheel
"mass production"	A mass-produced solution refers to a solution that has passed development and validation processes, met customer acceptance standards, and is ready for large-scale delivery
"MCU"	microcontroller unit, a chip that integrates a microprocessor core, memory, and peripheral interfaces, which is typically used to control the operation of embedded systems and is widely used in electronic products
"Mini LED"	mini light-emitting diode, a type of display backlight technology that uses significantly smaller LED chips to provide finer local dimming, enabling higher brightness, improved contrast and enhanced HDR performance in advanced display panels
"Micro LED"	micro light-emitting diode, a next-generation self-emissive display technology in which microscopic LED arrays serve as individual pixels, offering ultra-high brightness, wide color gamut, fast response time and long lifespan while supporting seamless modular displays
"nF"	nanofarads, a unit of electrical capacitance, representing one billionth of a Farad (F)
"OEM"	original equipment manufacturing, where a manufacturer manufactures a product in accordance with the customer's design and specifications and is marketed and sold under the customer's brand name or under no specific brand
"OLED"	organic light-emitting diode, a type of display technology in which organic materials emit light directly to produce images, enabling thinner, lighter and high-contrast screens
"PCBA"	printed circuit board assembly, printed circuit board is a board with electronic circuits connecting various components
"PCT"	the Patent Cooperation Treaty, which is an international patent law treaty, concluded in 1970. It provides a unified procedure for filing patent applications to protect inventions in each of its contracting states. A patent application filed under the PCT is called an international application, or PCT application
"RISC-V"	the fifth generation Reduced Instruction Set Computing architecture that is an open, flexible, efficient and innovative general instruction set architecture

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"R&D"	research and development
"SAR"	specific absorption rate, a measure of the amount of power deposited by a radiofrequency field in a certain mass of tissue
"scaler"	an image processing chip used for conversion of video format, resolution and refresh rate and image quality enhancement
"SCCU"	smart cockpit control units
"STDI"	Scaler TDDI
"SoC" or "system-on-chips"	programmable integrated circuit(s) that integrates central processing unit, memory interfaces, on-chip input/output devices, input/output interfaces and secondary storage interfaces
"sensor"	a device that measures or detects real-world conditions, such as capacitive sensing, pressure and temperature, and converts the conditions into analog or digital representations
"TDDI"	touch and display driver integration, a technology that combines touch functionality with the display driver in a single chip, simplifying the display structure and enhancing performance
"tape-out"	the completion of the final integrated circuit design before it is submitted to the foundry for manufacturing
"Tier 1 suppliers"	a company that supplies parts or systems directly to automotive OEMs. Other types of suppliers in the automotive industry include Tier 2 and Tier 3 suppliers. Tier 2 suppliers supply to Tier 1 suppliers. Tier 3 suppliers supply to Tier 2 suppliers
"TMCU"	touch MCU
"TPIC"	touch-panel IC
"TWS"	true wireless stereo, a type of wireless audio technology that allows for the creation of a stereo sound system without any physical wires connecting the audio devices
"wafer"	a thin slice of semiconductor, used for the fabrication of ICs and other microelectronic devices